



Material Content Data Sheet



Halogen-Free

Sales Product Name IPD90N04S3-H4

Issued

17. February 2022

MA# MA005698022

Package PG-TO252-3-11

Weight*

372.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.726	1.00	1.00	9993	9993
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.67	57.75	576705	577455
wire	non noble metal	aluminium	7429-90-5	5.518	1.48	1.48	14799	14799
encapsulation	inorganic material	zinc oxide	1314-13-2	1.221	0.33		3275	
	miscellaneous	miscellaneous	-	6.105	1.64		16375	
	plastics	epoxy resin	-	18.315	4.91		49125	
	inorganic material	silicon dioxide	60676-86-0	96.462	25.87	32.75	258724	327499
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10031	10031
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.063	0.02		169	
	noble metal	silver	7440-22-4	0.079	0.02		212	
	non noble metal	lead	7439-92-1	3.017	0.81	0.85	8093	8474
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51437	51504
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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